

ABSTRACT

On a leadframe on which to fix a photodetector element, an element mount frame and a fitting frame are laid with a gap left in between. A shielding frame for electromagnetically 5 shielding the photodetector element is tied, via a tying portion, not to the element mount frame but to the fitting frame. Bending the tying portion brings it into a state in which it covers the photodetector element, but the stress resulting from this bending of the tying portion is shut off by the gap so as not to spread to the element mount frame. On the element mount frame, a circuit element for processing the signal from the photodetector 10 element also is fixed.